ON Semiconductor

PRODUCT BULLETIN # 20510

Generic Copy

Issue Date: 12-Jun-2014

TITLE: NCP81022: Power On reset block modification

PROPOSED FIRST SHIP DATE: 12-Sep-2014

AFFECTED CHANGE CATEGORY(S): Die Part Change

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor sales office or <raymond.odell@onsemi.com>

NOTIFICATION TYPE:
ON Semiconductor considers this change approved unless specific conditions of acceptance are provided in writing. To do so, contact <quality@onsemi.com>.

DESCRIPTION AND PURPOSE:

To eliminate the possibility of an incorrect Power On reset, under high power supply slew rate conditions.

The solution was to bypass a redundant flip flop. This was an internal housekeeping signal only and did not have any impact on the functionality of the part.

The modification was implemented with a single layer metal mask change on the die.

No functionality or specification change with no change to the datasheet and no subsequent impact to the customer.

List of affected General Parts:

NCP81022MNTXG